



Material Content Data Sheet



Sales Product Name		TLE8242-2L		Issued		26. September 2017			
MA#		MA001063256							
Package		PG-LQFP-64-20		Weight*		384.43 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	23.915	6.22	6.22	62207	62207	
leadframe	inorganic material	phosphorus	7723-14-0	0.039	0.01		102		
		non noble metal	zinc	7440-66-6	0.156	0.04		407	
		non noble metal	iron	7439-89-6	3.128	0.81		8138	
wire	non noble metal	non noble metal	copper	7440-50-8	127.029	33.04	33.90	330430	339077
		non noble metal	copper	7440-50-8	0.858	0.22	0.22	2231	2231
		encapsulation	organic material	carbon black	1333-86-4	1.114	0.29		2899
encapsulation	plastics	plastics	epoxy resin	-	30.090	7.83		78271	
		inorganic material	silicondioxide	60676-86-0	191.684	49.88	58.00	498612	579784
		leadfinish	noble metal	palladium	7440-05-3	0.001	0.00		3
noble metal	silver			7440-22-4	0.001	0.00		2	
noble metal	gold			7440-57-5	0.002	0.00		5	
plating	non noble metal	non noble metal	nickel	7440-02-0	1.779	0.46	0.46	4627	4637
		noble metal	palladium	7440-05-3	0.000	0.00		1	
		non noble metal	nickel	7440-02-0	0.267	0.07		695	
glue	noble metal	noble metal	silver	7440-22-4	0.000	0.00		1	
		noble metal	gold	7440-57-5	0.000	0.00	0.07	1	696
		plastics	epoxy resin	-	1.093	0.28		2842	
*deviation	< 10%								
Sum in total:						100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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